

Sound Processor with Built-in 3-band Equalizer

BD37532FV

General Description

BD37532FV is a sound processor with built-in 3-band equalizer for car audio. A stereo input selector is available that functions to switch single end input and ground isolation input, input-gain control, main volume, loudness, 5ch fader volume and LPF for subwoofer. Moreover, "Advanced switch circuit", which is an original ROHM technology, can reduce various switching noise (ex. No-signal, low frequency like 20Hz & large signal inputs). Also, "Advanced switch" makes control of microcomputer easier, and constructs a high quality car audio system.

Features

- Reduced switching noise of input gain control, mute, main volume, fader volume, bass, middle, treble, loudness by using advanced switch circuit
- Built-in differential input selector that can make various combination of single-ended / differential input.
- Built-in ground isolation amplifier inputs, which is ideal for external stereo input.
- Built-in input gain controller reduces volume switching noise for portable audio input.
- Decreased number of external components due to built-in 3-band equalizer filter, LPF for subwoofer and loudness filter. It is possible to freely control Q, Gv, fo of 3-band equalizer and fc of LPF, Gv of loudness by I²C BUS control.
- A gain adjustment quantity of ±20dB with a 1 dB step gain adjustment is possible for bass, middle and treble.
- Equipped with terminals for subwoofer outputs. Also, the audio signal outputs of the front, rear and subwoofer can be chosen using the I²C BUS control.
- Energy-saving design resulting in low current consumption is achieved utilizing the BiCMOS process. It has the advantage in quality over scaling down the power heat control of the internal regulators.
- Input pins and output pins are organized and separately laid out in such a way that it simplifies the pattern layout of the PCB and decreases the board dimensions.
- It is possible to control I²C BUS with 3.3V / 5V.

Applications

It is optimal for car audio systems. It can also be used for audio equipments like mini Compo, micro Compo, TV etc.

Key Specifications

Power Supply Voltage Range: 7.0V to 9.5VCircuit Current (No Signal): 38mA(Typ)

■ Total Harmonic Distortion 1:

(FRONT, REAR) 0.001% (Typ)

■ Total Harmonic Distortion 2:

(SUBWOOFER) 0.002%(Typ)

■ Maximum Input Voltage: 2.3Vrms(Typ)

■ Crosstalk Between Selectors: -100dB(Typ)

Volume Control Range: +15dB to -79dB

Output Noise Voltage 1:

(FRONT,REAR) 3.8µVrms(Typ)

Output Noise Voltage 2:

 $\begin{array}{cc} (\text{SUBWOOFER}) & \text{4.8}\mu\text{Vrms}(\text{Typ}) \\ \text{Residual Output Noise Voltage:} & \text{1.8}\mu\text{Vrms}(\text{Typ}) \end{array}$

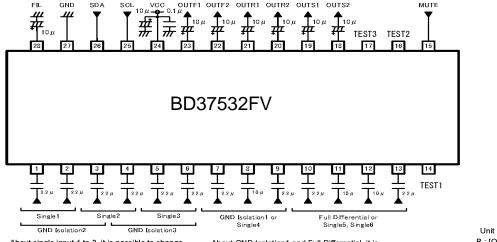
■ Operating Temperature Range: -40°C to +85°C

Package

 $W(Typ) \times D(Typ) \times H(Max)$



Typical Application Circuit

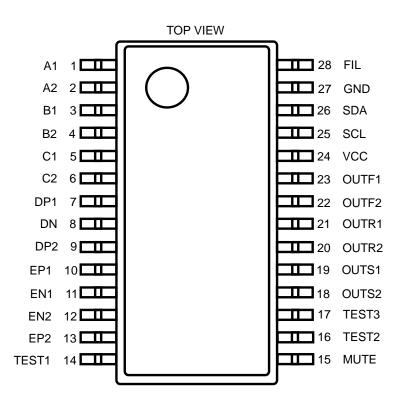


About single input 1 to 3, it is possible to change from single input to GND Isolation input 2,3.

About GND Isolation1 and Full Differential, it is possible to change from differential input to single input 4 to 6.

Unit R : [Ω] C : [F]

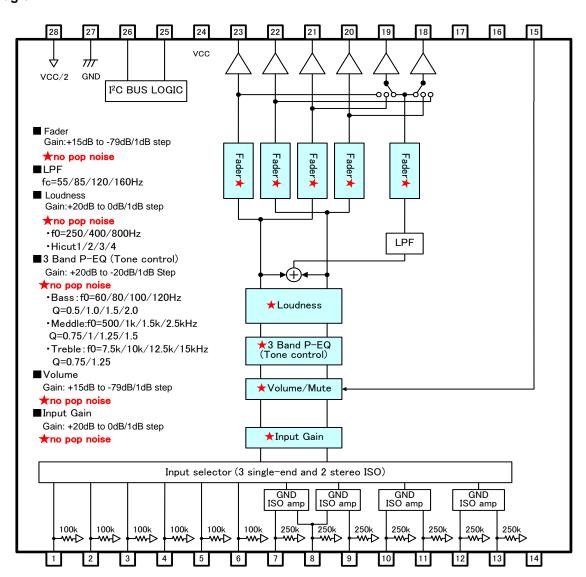
Pin Configuration



Pin Descriptions

Description	Ulia				
Pin No.	Pin Name	Description	Pin No.	Pin Name	Description
1	A1	A input terminal of 1ch	15	MUTE	External compulsory mute terminal
2	A2	A input terminal of 2ch	16	TEST2	Test pin
3	B1	B input terminal of 1ch	17	TEST3	Test pin
4	B2	B input terminal of 2ch	18	OUTS2	Subwoofer output terminal of 2ch
5	C1	C input terminal of 1ch	19	OUTS1	Subwoofer output terminal of 1ch
6	C2	C input terminal of 2ch	20	OUTR2	Rear output terminal of 2ch
7	DP1	D positive input terminal of 1ch	21	OUTR1	Rear output terminal of 1ch
8	DN	D negative input terminal	22	OUTF2	Front output terminal of 2ch
9	DP2	D positive input terminal of 2ch	23	OUTF1	Front output terminal of 1ch
10	EP1	E positive input terminal of 1ch	24	VCC	Power supply terminal
11	EN1	E negative input terminal of 1ch	25	SCL	I ² C Communication clock terminal
12	EN2	E negative input terminal of 2ch	26	SDA	I ² C Communication data terminal
13	EP2	E positive input terminal of 2ch	27	GND	GND terminal
14	TEST1	Test pin	28	FIL	VCC/2 terminal

Block Diagram



Absolute Maximum Ratings (Ta=25°C)

Parameter	Symbol	Rating	Unit
Power supply Voltage	Vcc	10.0	V
Input voltage	Vin	V _{CC} +0.3 to GND-0.3	V
Power Dissipation	Pd	1.06 ^(Note 1)	W
Storage Temperature	Tstg	-55 to +150	°C

(Note 1) When mounted on ROHM Standard board(70x70x1.6 (mm³), derate by 8.5mW/°C for Ta=25°C or more.

Thermal resistance θja = 117.6(°C/W)

Material: A FR4 grass epoxy board(3% or less of copper foil area)

Caution: Operating the IC over the absolute maximum ratings may damage the IC. The damage can either be a short circuit between pins or an open circuit between pins and the internal circuitry. Therefore, it is important to consider circuit protection measures, such as adding a fuse, in case the IC is operated over the absolute maximum ratings.

Recommended Operating Conditions

Parameter	Symbol	Limit	Unit
Power Supply Voltage	V _{CC}	7.0 to 9.5	V
Temperature	Topr	-40 to +85	°C

Electrical Characteristics

(Unless otherwise noted, Ta=25°C, Vcc=8.5V, f=1kHz, V $_{IN}$ =1Vrms, Rg=600 Ω , RL=10k Ω , A1 input, Input gain 0dB, Mute OFF, Volume 0dB, Tone control 0dB, Loudness 0dB, LPF OFF, Fader 0dB)

	OFF, volume dab, Tone control da 	b, Loudiness	Oub, Li i	Limit	iei oub)		
BLOCK	Parameter	Symbol	Min	Тур	Max	Unit	Conditions
	Circuit Current	IQ	-	38	48	mA	No signal
	Voltage Gain	G∨	-1.5	0	+1.5	dB	Gv=20log(Vout/Vin)
	Channel Balance	CB	-1.5	0	+1.5	dB	$CB = G_{V1} - G_{V2}$
	Total Harmonic Distortion 1 (FRONT,REAR)	THD+N1	-	0.001	0.05	%	V _{OUT} =1Vrms BW=400Hz-30KHz
	Total Harmonic Distortion 2 (SUBWOOFER)	THD+N2	-	0.002	0.05	%	V _{OUT} =1Vrms BW=400Hz-30KHz
AL AL	Output Noise Voltage 1 (FRONT,REAR) *	V _{NO1}	-	3.8	15	μVrms	$Rg = 0\Omega$ BW = IHF-A
GENERAL	Output Noise Voltage 2 (SUBWOOFER) *	V _{NO2}	-	4.8	15	μVrms	$Rg = 0\Omega$ BW = IHF-A
GE	Residual Output Noise Voltage	Vnor	-	1.8	10	μVrms	Fader = -∞dB Rg = 0Ω BW = IHF-A
	Crosstalk Between Channels*	СТС	-	-100	-90	dB	$Rg = 0\Omega$ $CTC=20log(V_{OUT}/V_{IN})$ $BW = IHF-A$
	Ripple Rejection	RR	-	-70	-40	dB	f=1kHz V _{RR} =100mVrms RR=20log(V _{CC} IN/V _{OUT})
	Input Impedance (A, B, C)	R _{IN_S}	70	100	130	kΩ	
	Input Impedance (D, E)	R _{IN_D}	175	250	325	kΩ	
TOR	Maximum Input Voltage	V _{IM}	2.1	2.3	-	Vrms	V _{IM} at THD+N(V _{OUT})=1% BW=400Hz-30KHz
T SELECTOR	Crosstalk Between Selectors *	стѕ	-	-100	-90	dB	Rg = 0Ω CTS=20log(V _{OUT} /V _{IN}) BW = IHF-A
INPUT	Common Mode Rejection Ratio * (D, E)	CMRR	50	65	-	dB	XP1 and XN input XP2 and XN input CMRR=20log(V _{IN} /V _{OUT}) BW = IHF-A,[*X···D,E]

Electrical Characteristics – continued

ectrical	Characteristics – continue						
BLOCK	Parameter	Symbol		Limit	1	Unit	Conditions
BL(T dramotor	Cymbol	Min	Тур	Max	OTIL	
GAIN	Minimum Input Gain	GIN_MIN	-2	0	+2	dB	Input gain 0dB V _{IN} =100mVrms G _{IN} =20log(V _{OUT} /V _{IN})
INPUT	Maximum Input Gain	G _{IN_MAX}	+18	+20	+22	dB	Input Gain +20dB V _{IN} =100mVrms G _{IN} =20log(V _{OUT} /V _{IN})
	Gain Set Error	G _{IN_ERR}	-2	0	+2	dB	Gain=+20dB to +1dB
MUTE	Mute Attenuation *	G _{мите}	-	-105	-85	dB	Mute ON G _{MUTE} =20log(V _{OUT} /V _{IN}) BW = IHF-A
	Maximum Gain	G _{V_MAX}	13	15	17	dB	Volume = 15dB V _{IN} =100mVrms Gv=20log(V _{OUT} /V _{IN})
VOLUME	Maximum Attenuation *	G _{V_MIN}	-	-100	-85	dB	Volume = -∞dB Gv=20log(V _{OUT} /V _{IN}) BW = IHF-A
	Attenuation Set Error 1	G _{V_ERR1}	-2	0	+2	dB	GAIN & ATT=+15dB to -15dB
	Attenuation Set Error 2	G _{V_ERR2}	-3	0	+3	dB	ATT=-16dB to -47dB
	Attenuation Set Error 3	G _{V_ERR3}	-4	0	+4	dB	ATT=-48dB to -79dB
(O	Maximum Boost Gain	G _{B_BST}	18	20	22	dB	Gain=+20dB f=100Hz V _{IN} =100mVrms GB=20log (V _{OUT} /V _{IN})
BASS	Maximum Cut Gain	G в_сит	-22	-20	-18	dB	Gain=-20dB f=100Hz V _{IN} =2Vrms GB=20log (V _{OUT} /V _{IN})
	Gain Set Error	G _{B_ERR}	-2	0	+2	dB	Gain=+20dB to -20dB f=100Hz
)LE	Maximum Boost Gain	G м_вѕт	18	20	22	dB	Gain=+20dB f=1KHz V _{IN} =100mVrms GM=20log (V _{OUT} /V _{IN})
MIDDLE	Maximum Cut Gain	G м_сит	-22	-20	-18	dB	Gain=-20dB f=1kHz V _{IN} =2Vrms GM=20log (V _{OUT} /V _{IN})
	Gain Set Error	G _{M_ERR}	-2	0	+2	dB	Gain=+20dB to -20dB f=1kHz Gain=+20dB f=10kHz
Щ	Maximum Boost Gain	G _{T_BST}	18	20	22	dB	V _{IN} =100mVrms GT=20log (V _{OUT} /V _{IN})
TREBL	Maximum Cut Gain	G т_сит	-22	-20	-18	dB	Gain=-20dB f=10kHz V _{IN} =2Vrms GT=20log (V _{OUT} /V _{IN})
	Gain Set Error	G _{T_ERR}	-2	0	+2	dB	Gain=+20dB to -20dB f=10kHz
 X	Maximum Boost Gain	G _{F_BST}	13	15	17	dB	Fader=15dB V _{IN} =100mVrms G _F =20log(V _{OUT} /V _{IN})
FADER / SUBWOOFER	Maximum Attenuation *	G _{F_MIN}	-	-100	-90	dB	Fader = -∞dB GF=20log(V _{OUT} /V _{IN}) BW = IHF-A
J.B.	Gain Set Error	G _{F_ERR}	-2	0	+2	dB	Gain=+15dB to +1dB
S	Attenuation Set Error 1	GF_ERR1	-2	0	+2	dB	ATT=-1dB to -15dB
8	Attenuation Set Error 2	GF_ERR2	-3	0	+3	dB	ATT=-16dB to -47dB
円	Attenuation Set Error 3	G _{F_ERR3}	-4	0	+4	dB	ATT=-48dB to -79dB
FAI	Output Impedance	Rout	-	-	50	Ω	V _{IN} =100mVrms
	Maximum Output Voltage	V _{OM}	2	2.2	-	Vrms	THD+N=1% BW=400Hz-30KHz
ZESS	Maximum Gain	GL_MAX	17	20	23	dB	Gain 20dB V _{IN} =100mVrms GL=20log(V _{OUT} /V _{IN})
LOUDNESS	Gain Set Error	G _{L_ERR}	-2	0	+2	dB	GAIN=+20dB to +1dB

VP-9690A (Average value detection, effective value display) filter by Matsushita Communication is used for * measurement. Phase between input / output is same.

Typical Performance Curves

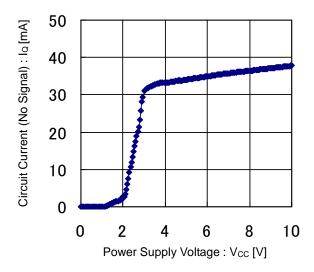


Figure 1. Circuit Current (No Signal) vs Power Supply Voltage

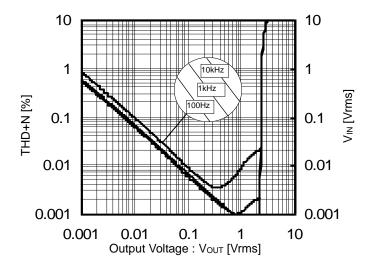


Figure 2. Total Harmonic Distortion vs Output Voltage

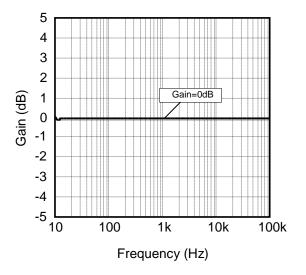


Figure 3. Gain vs Frequency

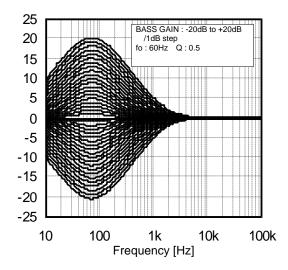


Figure 4. Bass Gain vs Frequency

Gain[dB]

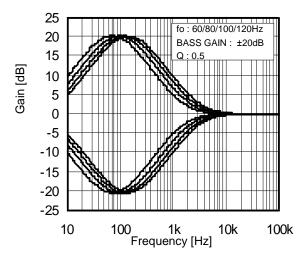


Figure 5. Bass fo vs Frequency

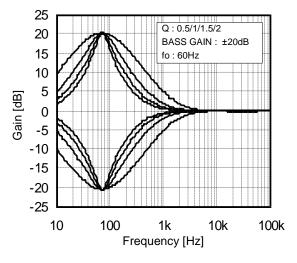


Figure 6. Bass Q vs Frequency

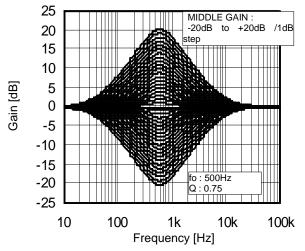


Figure 7. Middle Gain vs Frequency

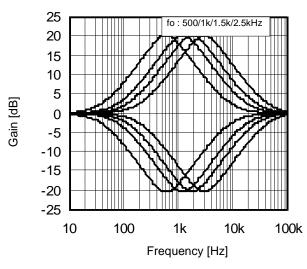


Figure 8. Middle fo vs Frequency

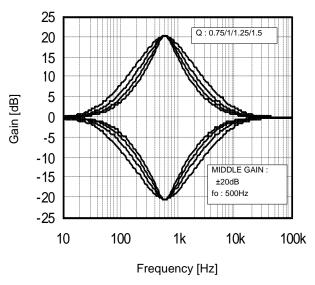


Figure 9. Middle Q vs Frequency

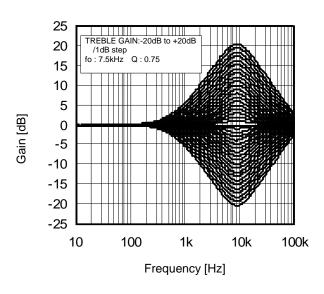


Figure 10. Treble Gain vs Frequency

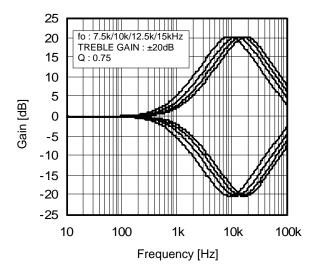


Figure 11. Treble fo vs Frequency

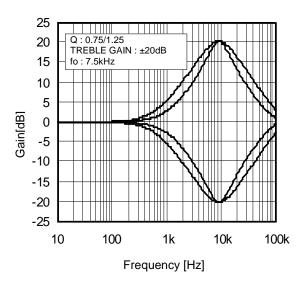


Figure 12. Treble Q vs Frequency

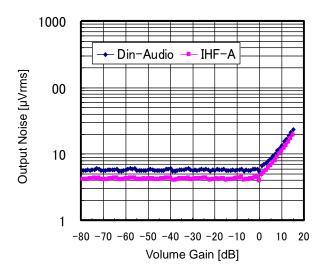


Figure 13. Output Noise vs Volume Gain

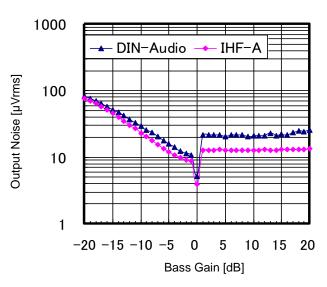


Figure 14. Output Noise vs Bass Gain

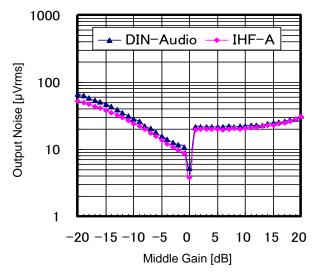


Figure 15. Output Noise vs Middle Gain

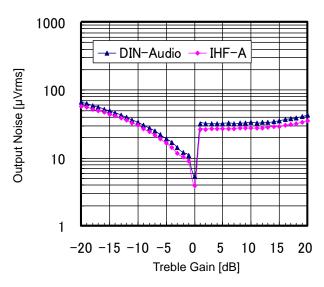
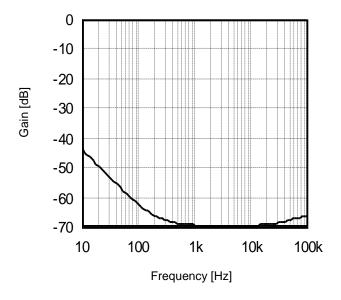


Figure 16. Output Noise vs Treble Gain



2.5

2.0

1.5

1.0

0.5

0.0

100

1000

10000

100000

RLOAD [ohm]

Figure 17. CMRR vs Frequency

Figure 18. Output Voltage vs R_{LOAD}

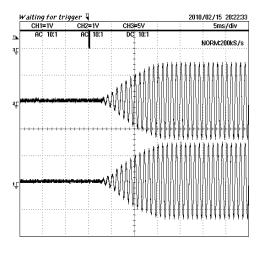


Figure 19. Advanced Switch 1

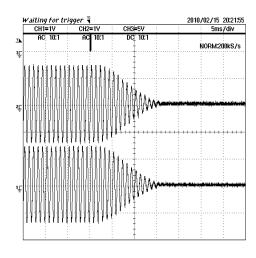


Figure 20. Advanced Switch 2

Timing Chart

CONTROL SIGNAL SPECIFICATION

(1) Electrical Specifications and Timing for Bus Lines and I/O Stages

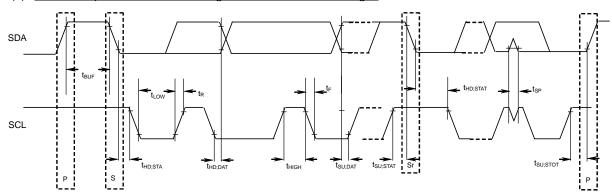


Figure 21. Definition of Timing on the I²C-bus

Table 1 Characteristics of the SDA and SCL bus lines for I^2 C-bus devices (Unless specified particularly, Ta=25°C, V_{CC} =8.5V)

	Parameter	Cumbal	Fast-mod	e I ² C-bus	Unit
	Parameter	Symbol	Min	Min Max	
1	SCL clock frequency	f _{SCL}	0	400	kHz
2	Bus free time between a STOP and START condition	t BUF	1.3	-	μS
3	Hold time (repeated) START condition. After this period, the first clock	tup oza	0.6		μS
?	pulse is generated	t HD;STA	0.6	-	μδ
4	LOW period of the SCL clock	t_{LOW}	1.3	-	μS
5	HIGH period of the SCL clock	tніgн	0.6	-	μS
6	Set-up time for a repeated START condition	tsu;sta	0.6	-	μS
7	Data hold time:	t _{HD;DAT}	0.06 ^(Note)	-	μS
8	Data set-up time	tsu;dat	120	-	ns
9	Set-up time for STOP condition	tsu;sto	0.6	-	μS

All values referred to VIH Min and VIL Max Levels (see Table 2).

(Note) The device must internally provide a hold time of at least 300 ns for the SDA signal (referred to the VIH Min of the SCL signal) in order to bridge the undefined region of the falling edge of SCL.

About 7 ($t_{\text{HD;DAT}}$), 8($t_{\text{SU;DAT}}$), make the setup in which the margin is fully in .

Table 2 Characteristics of the SDA and SCL I/O stages for I²C-bus devices

	Parameter	Cumbal	Fast-mode	Unit	
	Parameter	Symbol	Min	Max	Onit
10	LOW level input voltage:	VIL	-0.3	+1	V
11	HIGH level input voltage:	V _{IH}	2.3	5	V
12	Pulse width of spikes which must be suppressed by the input filter.	tsp	0	50	ns
13	LOW level output voltage: at 3mA sink current	V _{OL1}	0	0.4	V
14	Input current each I/O pin with an input voltage between 0.4V and 4.5V.	I _I	-10	+10	μΑ

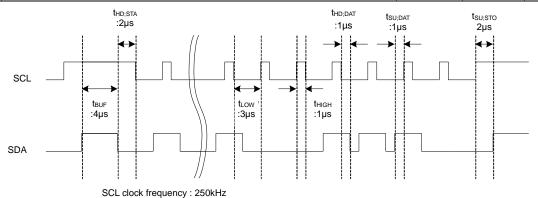


Figure 22. A Command Timing Example in the I²C Data Transmission

(2) <u>I²C BUS FORMAT</u>

	MSB	LSB		MSB	LSB		MSB		LSB		
S	Slave Ad	ldress	Α	Select Addre	SS	Α		Data		Α	Р
1bit	8bit	t	1bit	8bit		1bit		8bit		1bit	1bit
	S		= Sta	art conditions (Re	cognit	ion of	start bit)				
	Slave A	Address	= Re	cognition of slav	e addr	ess. 7	' bits in up	per orde	r are v	olunta	ary.
			The	e least significan	t bit is	"L" fo	r write mo	de.			
	Α		= ACKNOWLEDGE bit (Recognition of acknowledgement)								
	Select	Address	= Select address for volume, bass and treble.								
	Data		= Data on every volume and tone.								
	Р		= Sto	op condition (Red	canitic	on of s	stop bit)				

(3) I²C BUS Interface Protocol

/ \		•
121	Basic	torm
(a)	Dasic	101111

<u>(u)</u>	Jacio Ioiiii								
S	Slave Addre	ess	Α	Select A	Address	Α	Data	Α	Ρ
	MSB			MSB	LSB	M	ISB	LSB	

(b) Automatic increment (Select Address increases (+1) according to the number of data.

S	Slave Address	Α	Select Address	Α	Data1	Α	D	ata2	Α	 DataN	Α	Р
	MSB LSB	MS	SB LSB	MS	B LSB	N	1SB	LSB		MSB	LSB	

(Example) ①Data1 shall be set as data of address specified by Select Address.

- ②Data2 shall be set as data of address specified by Select Address +1.
- ③DataN shall be set as data of address specified by Select Address +N-1.

(c) Configuration unavailable for transmission (In this case, only Select Address1 is set.

70		ringaration and						ouo	<u>, oi</u>	ny core	ot / taart	JUU 1 10	, 00	٠.			
0)	SS	lave Address	Α	Select A	Address1	Α	Da	ata	Α	Selec	ct Addre	ss 2	Α	Da	ta	Α	Р
	MSB	LSB		MSB	LSB	N	1SB	LS	SB	MSB		LSB	Μ	ISB	LS	В	
		(Note) If any	data	a is transn	nitted as Se	elec	t Ado	dress	2 n	ext to c	lata, it is	recog	gniz	ed			
		as c	lata.	not as Se	elect Addres	ss 2	2.										

(4) Slave Address

MSB							LSB	
A6	A5	A4	A3	A2	A1	A0	R/W	
1	0	0	0	0	0	0	0	80H

(5) Select Address & Data

Items	Select Address	MSB			Di	ata			LSB		
items	(hex)	D7	D6	D5	D4	D3	D2	D1	D0		
Initial setup 1	01	Advanced switch ON/OFF	0	of Input Ga Tone/Fade	switch time ain/Volume r/Loudness	0	1		switch time /lute		
Initial setup 2	02	LPF Phase	0		fer Output 0 Subwoofer LPF fc						
Initial setup 3	03	0	0	0	Loudn	ess fo	0	0	1		
Input Selector	05	Full-diff Type	0	0		ı	nput selecto	or			
Input gain	06	Mute ON/OFF	0	0			Input Gain				
Volume gain	20			\	Volume Gain / Attenuation						
Fader 1ch Front	28			Fader Gain / Attenuation							
Fader 2ch Front	29		Fader Gain / Attenuation								
Fader 1ch Rear	2A		Fader Gain / Attenuation								
Fader 2ch Rear	2B				Fader Gain	/ Attenuation	1				
Fader Subwoofer	2C				Fader Gain	/ Attenuation	1				
Test Mode	30	1	1	1	1	1	1	1	1		
Bass setup	41	0	0	Bas	s fo	0	0	Bas	ss Q		
Middle setup	44	0	0	Midd	lle fo	0	0	Midd	dle Q		
Treble setup	47	0	0	Treb	le fo	0	0	0	Treble Q		
Bass gain	51	Bass Boost/ Cut	0	0			Bass Gain				
Middle gain	54	Middle Boost/ Cut	0	0	Middle Gain						
Treble gain	57	Treble Boost/ Cut	0	0	Treble Gain						
Loudness Gain	75	0	Loudn	ess Hicut		L	oudness Ga	in			
System Reset	FE	1	0	0	0	0	0	0	1		

Advanced switch

Note

- 1. The Advanced Switch works in the latch part while changing from one function to another..
- 2. Upon continuous data transfer, the Select Address rolls over because of the automatic increment function, as shown below.

$$01 \rightarrow 02 \rightarrow 03 \rightarrow 05 \rightarrow 06 \rightarrow 20 \rightarrow 28 \rightarrow 29 \rightarrow 2A \rightarrow 2B \rightarrow 2C$$

$$\rightarrow 30 \rightarrow 41 \rightarrow 44 \rightarrow 47 \rightarrow 51 \rightarrow 54 \rightarrow 57 \rightarrow 75$$

- 3. Advanced Switch is not used for the functions of input selector and subwoofer output select etc. Please turn on MUTE when changing the settings of this side of the set.
- When using Mute function of this IC at the time of changing input selector, please switch mute ON/OFF while waiting for advanced-mute time.

Select address 01 (hex)

Time	MSB	Ad	Advanced switch time of Mute L							
Time	D7	D6	D5	D4	D3	D2	D1	D0		
0.6msec	A alven a a al		A al. (2 2 2 2 2 d	avvitale time e			0	0		
1.0msec	Advanced Switch	0		switch time	_	_	0	1		
1.4msec	ON/OFF	U		ain/Volume er/Loudness	0	'	1	0		
3.2msec	ON/OFF		TOTIE/Faut	ei/Loudiless			1	1		

Time	MSB	Advanced switch time of Input gain/Volume/Tone/Fader/Loudness							
	D7	D6	D5	D4	D3	D2	D1	D0	
4.7 msec	A alv (a va a a a a		0	0					
7.1 msec	Advanced Switch ON/OFF	0	0	1	0	1	Advanced switch Time of Mute		
11.2 msec			1	0	U	'			
14.4 msec	ON/OFF		1	1					

Mode	MSB		Advan	ced sv	vitch C	N/OFI	F	LSB
Wiode	D7	D6	D5	D2	D1	D0		
OFF	0	0	Advanced switch time 0 of Input gain/Volume Tone/Fader/Loudness		0	0 1		ed switch
ON	1						Time of Mute	

Select address 02(hex)

Coloot dadiood oz(llox	/								
fo	MSB Subwoofer LPF fc								
tc	D7	D6	D5	D4	D3	D2	D1	D0	
OFF						0	0	0	
55Hz						0	0	1	
85Hz	I DE Dhasa	0	Subwoofer Output			0	1	0	
120Hz	LPF Phase		Sele	lect	0	0	1	1	
160Hz						1	0	0	
Prohibition							Other setting	3	

Mode	MSB	Subwoofer Output Select I							
iviode	D7	D6	D5	D4	D3	D2	D1	D0	
LPF			0	0					
Front		0	0	1				- ,	
Rear	LPF Phase	0	1	0	0	Su	bwoofer LPF	- IC	
Prohibition			1	1					

Phase	MSB	B LPF Phase								
Filase	D7	D6 D5 D4 D3 D2 D1								
0°	0	0	Subwoot	fer output	0	Qu	Subwoofer LPF fc			
180° 1			se	lect	U	Su	DWOOIEI LEI	- IC		

Select address 03(hex)

fO	MSB		Loudness fo LS							
10	D7	D6	D5	D4	D3	D2	D1	D0		
250Hz				0	0					
400Hz	0	_	_	0	1	0	0 0	,		
800Hz	U	U	U	1	0] 0	U	1		
Prohibition				1	1					

	Initial	condition

Select address 05(hex)

Mode		•	MSB		Ir	put S	Select	or		LSB	
Mode	OUTF1	OUTF2	D7	D6	D5	D4	D3	D2	D1	D0	
Α	A1	A2		rpe 0		0	0	0	0	0	
В	B1	B2				0	0	0	0	1	
С	C1	C2					0	0	0	1	0
D single	DP1	DP2				0	0	0	1	1	
E1 single	EP1	EN1	FII 4:44			0	1	0	1	0	
E2 single	EN2	EP2	Full-diff		0	0	1	0	1	1	
A diff	A1	B1	bias type select		0	0	1	1	1	1	
C diff	B2	C2	Select			1	0	0	0	0	
D diff	DP1	DP2				0	0	1	1	0	
E full diff	EP1	EP2					0	1	0	0	0
Inp	ut SHORT					0	1	0	0	1	
Prohibition							Other setting	3			

Input SHORT : The input impedance of each input terminal is lowered from $100k\Omega(Typ)$ to $6~k\Omega(Typ)$. (For quick charge of coupling capacitor)

Mode	мѕв	MSB Full-diff Bias Type Select							
	D7	D6	D5	D4	D3	D2	D1	D0	
Negative Input	0	0	0			nput Selecto	r	D0	
Bias	1	0	0		'	nput Selecto	"		

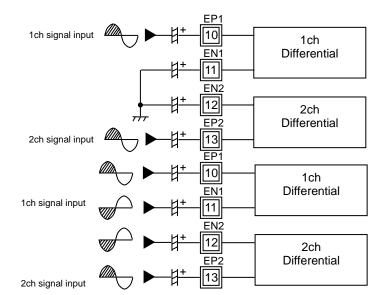
: Initial condition

Negative input type

For Ground -isolation type)

Bias type

For differential amplifier type



Select address 06 (hex)

Gain	MSB			Input	Gain			LSB
Gaill	D7	D6	D5	D4	D3	D2	D1	D0
0dB				0	0	0	0	0
1dB				0	0	0	0	1
2dB				0	0	0	1	0
3dB				0	0	0	1	1
4dB				0	0	1	0	0
5dB				0	0	1	0	1
6dB				0	0	1	1	0
7dB				0	0	1	1	1
8dB				0	1	0	0	0
9dB				0	1	0	0	1
10dB				0	1	0	1	0
11dB	Mute	0	0	0	1	0	1	1
12dB	ON/OFF	U	U	0	1	1	0	0
13dB				0	1	1	0	1
14dB				0	1	1	1	0
15dB				0	1	1	1	1
16dB				1	0	0	0	0
17dB				1	0	0	0	1
18dB				1	0	0	1	0
19dB				1	0	0	1	1
20dB				1	0	1	0	0
				1	1	0	1	1
Prohibition				:	:	:.	:	:
				1	1	1	1	1

Mode	MSB		Mute ON/OFF LS						
Wiode	D7	D6	D5	D4	D3	D2	D1	D0	
OFF	0	0	0			Innut Cain			
ON	1	U	U			Input Gain			

Select address 20, 28, 29, 2A, 2B, 2C (hex)

Gain & ATT	MSB	Vo	ol, Fad	er Gai	n / Atte	enuatio	on	LSB
Gaill & All I	D7	D6	D5	D4	D3	D2	D1	D0
	0	0	0	0	0	0	0	0
B 1999	0	0	0	0	0	0	0	1
Prohibition	:	:	:	:	:	:	:	:
	0	1	1	1	0	0	0	0
15dB	0	1	1	1	0	0	0	1
14dB	0	1	1	1	0	0	1	0
13dB	0	1	1	1	0	0	1	1
:	:	:	:	:	:	:	:	:
-77dB	1	1	0	0	1	1	0	1
-78dB	1	1	0	0	1	1	1	0
-79dB	1	1	0	0	1	1	1	1
	1	1	0	1	0	0	0	0
Prohibition	:	:		:	÷	:	:	:
	1	1	1	1	1	1	1	0
-∞dB	1	1	1	1	1	1	1	1

Select address 41(hex)

Q factor	MSB		Bass Q factor L					LSB
Q lactor	D7	D6	D5	D4	D3	D2	D1	D0
0.5							0	0
1.0	0	0	Pac	ss fo	_	0	0	1
1.5	U	U	Das	55 10			1	0
2.0							1	1

fo	MSB			Bass	LSB			
fo	D7	D6	D5	D4	D3	D2	D1	D0
60Hz			0	0				•
80Hz	0	0	0	1	_	0	Ba	ass actor
100Hz	U	U	1	0		U	Q fa	actor
120Hz			1	1				

Select address 44(hex)

Q factor	MSB		Mic	ddle	Q facto	or	LSB	
Q lactor	D7	D6	D5	D4	D3	D2	D1	D0
0.75							0	0
1.0]	0	Mida	dle fo		_	D1 0 0 1	1
1.25] 0	U	ivilde	ile io	0	U	1	0
1.5							1	1

	1								
fo	MSB			Middle	e fo		LSB		
TO	D7	D6	D5	D4	D3	D2	D1	D0	
500Hz			0	0					
1kHz		0	0	1]	0	Mid	ddle	
1.5kHz	7 0	U	1	0] 0	U	Q fa	actor	
2.5kHz			1	1					

Select address 47 (hex)

Q factor	MSB		Tre	eble	Q facto	or		LSB		
Q lactor	D7	D6	D5	D4	D3	D2	D1	D0		
0.75	0	0	Troh	ole fo	0	0	0	0		
1.25	U	U	rrec	ne io	U	U	U	1		

fo	MSB			Treble	e fo			LSB
TO	D7	D6	D5	D4	D3	D2	D1	D0
7.5kHz			0	0				
10kHz		0	0	1	_	0	0	Treble Q factor
12.5kHz] "	0	1	0	0	U	0	Q factor
15kHz			1	1				

Select address 51, 54, 57 (hex)

Select address 51, 54, 57 (hex) MSB Bass/Middle/Treble Gain LSB								
Gain	MSB	E	3ass/N	<u>/liddle/</u>	Treble	Gain		LSB
Gain	D7	D6	D5	D4	D3	D2	D1	D0
0dB				0	0	0	0	0
1dB				0	0	0	0	1
2dB				0	0	0	1	0
3dB				0	0	0	1	1
4dB				0	0	1	0	0
5dB				0	0	1	0	1
6dB				0	0	1	1	0
7dB				0	0	1	1	1
8dB				0	1	0	0	0
9dB				0	1	0	0	1
10dB	Bass/			0	1	0	1	0
11dB	Middle/			0	1	0	1	1
12dB	Treble	0	0	0	1	1	0	0
13dB	Boost			0	1	1	0	1
14dB	/cut			0	1	1	1	0
15dB				0	1	1	1	1
16dB				1	0	0	0	0
17dB				1	0	0	0	1
18dB				1	0	0	1	0
19dB				1	0	0	1	1
20dB				1	0	1	0	0
				1	0	1	0	1
Prohibition				:	:	:	:	:
1 101110111				1	1	1	1	0
				1	1	1	1	1

Mode	MSB	Bas	Bass/Middle/Treble Boost/Cut LSB					
iviode	D7	D6	D5	D4	D3	D2	D1	D0
Boost	0	0	0		Pose/	Middle/Treble	o Coin	•
Cut	1	U	0					

Select address 75 (hex)

001001 4441033 70 (110	,^)							
Mode	MSB		L		LSB			
iviode	D7	D6	D5	D4	D3	D2	D1	D0
Hicut1		0	0					
Hicut2	٦ ,	0	1					
Hicut3		1	0	Loudness Gain				
Hicut4		1	1					

Gain	MSB		L	.oudne	ss Ga	in		LSB						
Gaill	D7	D6	D5	D4	D3	D2	D1	D0						
0dB				0	0	0	0	0						
1dB				0	0	0	0	1						
2dB				0	0	0	1	0						
3dB				0	0	0	1	1						
4dB				0	0	1	0	0						
5dB				0	0	1	0	1						
6dB				0	0	1	1	0						
7dB				0	0	1	1	1						
8dB				0	1	0	0	0						
9dB				0	1	0	0	1						
10dB				0	1	0	1	0						
11dB		0 Loudness Hick	Loudness Hic	oudness Hicut	0	1	0	1	1					
12dB	0				Loudness Hicut	0	1	1	0	0				
13dB				0	1	1	0	1						
14dB				0	1	1	1	0						
15dB		l								0	1	1	1	1
16dB				1	0	0	0	0						
17dB				1	0	0	0	1						
18dB				1	0	0	1	0						
19dB				1	0	0	1	1						
20dB				1	0	1	0	0						
				1	0	1	0	1						
Prohibition				:	:	:	:	:						
				1	1	1	1	1						

: Initial Condition

(6) About Power ON Reset

Built-in IC initialization is made during power ON of the supply voltage. Please send initial data to all addresses at supply voltage on. Also, please turn ON MUTE at the set side until initial data is sent.

Parameter	Symbol		Limit		Unit	Conditions	
Farameter	Symbol	Min	Тур	Max	Offic		
Rise Time of VCC	trise	33	-	-	µsec	V _{CC} rise time from 0V to 5V	
VCC Voltage of Release Power ON Reset	V _{POR}	-	4.1	-	V		

(7) About External Compulsory Mute Terminal

It is possible to forcibly set Mute from the outside by setting input voltage at the MUTE terminal.

Mute Voltage Condition	Mode
GND to 1.0V	MUTE ON
2.3V to Vcc	MUTE OFF
2.3V to VCC	MUTE OFF

Establish the voltage of MUTE in the condition to be defined.

Application Information

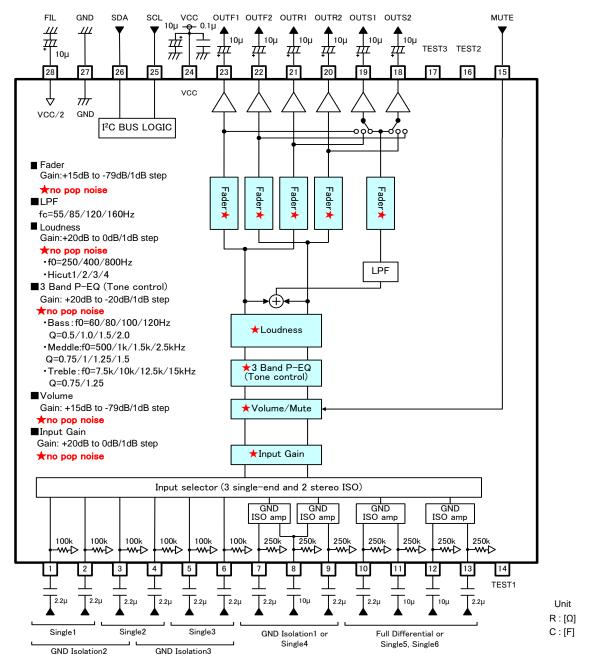
1. Function and Specifications

Function	Specifications									
	· (Stereo inp	out)								
	· Single-End/Diff/Full-Diff									
	(Possible to set the number of single-end/diff/full-diff as follows)									
	Single-End Differential Full-Differential									
Input	Mode 1	0	3	1						
selector	Mode 2 Mode 3	<u> </u>	<u>2</u> 1	1						
	Mode 4	<u> </u>	0	1						
	Mode 5	5	1	0						
	Mode 6	6	0	0						
			ombination of inp	out selector						
Input		0dB (1dB step)								
gain	Possible	to use "Advanc	ed switch" for pre	evention of switching	noise.					
Mute	Possible	to use "Advance	ed switch" for pre	evention of switching	noise.					
Volume	· +15dB to	-79dB (1dB ste	:p), -∞dB							
Totallie	Possible to use "Advanced switch" for prevention of switching noise.									
	· +20dB to -20dB (1dB step)									
Bass	· Q=0.5, 1, 1.5, 2									
Dass	· fo=60, 80, 100, 120Hz									
	Possible to use "Advanced switch" when changing gain									
	· +20dB to -20dB (1dB step)									
Middle	· Q=0.75, 1, 1.25, 1.5									
Wildale	· fo=500, 1k, 1.5k 2.5kHz									
	Possible to use "Advanced switch" when changing gain									
	· +20dB to	-20dB (1dB ste	ep)							
Treble	· Q=0.75, 1.25									
Hebie	· fo=7.5k, 10k, 12.5k, 15kHz									
	Possible to use "Advanced switch" when changing gain									
Fader	· +15dB to -79dB(1dB step), -∞dB									
i adei	Possible to use "Advanced switch" for prevention of switching noise.									
	· +20dB to	0dB(1dB step)								
Loudness	· fo=250/40	00/800Hz								
	Possible	to use "Advanc	ed switch" for pre	evention of switching	noise.					
LPF	· fc=55/85/	120/160Hz, pas	SS							
LFF	· Phase sh	ift (0°/180°)								

2. Volume / Fader Volume Attenuation Data

Z. Volulile	, , ı u	JC: VC	, a i i i	Allei	Idatic	711 Du	ıu										
(dB)	D7	D6	D5	D4	D3	D2	D1	D0	(dB)	D7	D6	D5	D4	D3	D2	D1	D0
+15	0	1	1	1	0	0	0	1	-33	1	0	1	0	0	0	0	1
+14	0	1	1	1	0	0	1	0	-34	1	0	1	0	0	0	1	0
+13	0	1	1	1	0	0	1	1	-35	1	0	1	0	0	0	1	1
+12	0	1	1	1	0	1	0	0	-36	1	0	1	0	0	1	0	0
+11	0	1	1	1	0	1	0	1	-37	1	0	1	0	0	1	0	1
+10	0	1	1	1	0	1	1	0	-38	1	0	1	0	0	1	1	0
+9	0	1	1	1	0	1	1	1	-39	1	0	1	0	0	1	1	1
+8	0	1	1	1	1	0	0	0	-40	1	0	1	0	1	0	0	0
+7	0	1	1	1	1	0	0	1	-41	1	0	1	0	1	0	0	1
+6	0	1	1	1	1	0	1	0	-42	1	0	1	0	1	0	1	0
+5	0	1	1	1	1	0	1	1	-43	1	0	1	0	1	0	1	1
+4	0	1	1	1	1	1	0	0	-44	1	0	1	0	1	1	0	0
+3	0	1	1	1	1	1	0	1	-45	1	0	1	0	1	1	0	1
+2	0	1	1	1	1	1	1	0	- 4 5	1	0	1	0	1	1	1	0
+1	0	1	1	1	1	1	1	1	-47	1	0	1	0	1	1	1	1
0	1	0	0	0	0	0	0	0	-48	1	0	1	1	0	0	0	0
-1	1	0	0	0	0	0	0	1	-49	1	0	1	1	0	0	0	1
-2	1	0	0	0	0	0	1	0	-50	1	0	1	1	0	0	1	0
-3	1	0	0	0	0	0	1	1	-51	1	0	1	1	0	0	1	1
-4	1	0	0	0	0	1	0	0	-52	1	0	1	1	0	1	0	0
-5	1	0	0	0	0	1	0	1	-53	1	0	1	1	0	1	0	1
-6	1	0	0	0	0	1	1	0	-54	1	0	1	1	0	1	1	0
-7	1	0	0	0	0	1	1	1	-55	1	0	1	1	0	1	1	1
-8	1	0	0	0	1	0	0	0	-56	1	0	1	1	1	0	0	0
-9	1	0	0	0	1	0	0	1	-57	1	0	1	1	1	0	0	1
-10	1	0	0	0	1	0	1	0	-58	1	0	1	1	1	0	1	0
-11	1	0	0	0	1	0	1	1	-59	1	0	1	1	1	0	1	1
-12	1	0	0	0	1	1	0	0	-60	1	0	1	1	1	1	0	0
-13	1	0	0	0	1	1	0	1	-61	1	0	1	1	1	1	0	1
-14	1	0	0	0	1	1	1	0	-62	1	0	1	1	1	1	1	0
-15	1	0	0	0	1	1	1	1	-63	1	0	1	1	1	1	1	1
-16	1	0	0	1	0	0	0	0	-64	1	1	0	0	0	0	0	0
-17	1	0	0	1	0	0	0	1	-65	1	1	0	0	0	0	0	1
-18	1	0	0	1	0	0	1	0	-66	1	1	0	0	0	0	1	0
-19	1	0	0	1	0	0	1	1	-67	1	1	0	0	0	0	1	1
-20	1	0	0	1	0	1	0	0	-68	1	1	0	0	0	1	0	0
-21	1	0	0	1	0	1	0	1	-69	1	1	0	0	0	1	0	1
-22	1	0	0	1	0	1	1	0	-70	1	1	0	0	0	1	1	0
-23	1	0	0	1	0	1	1	1	-71	1	1	0	0	0	1	1	1
-24	1	0	0	1	1	0	0	0	-72	1	1	0	0	1	0	0	0
-25	1	0	0	1	1	0	0	1	-73	1	1	0	0	1	0	0	1
-26	1	0	0	1	1	0	1	0	-74	1	1	0	0	1	0	1	0
-27	1	0	0	1	1	0	1	1	-75	1	1	0	0	1	0	1	1
-28	1	0	0	1	1	1	0	0	-76	1	1	0	0	1	1	0	0
-29	1	0	0	1	1	1	0	1	-77	1	1	0	0	1	1	0	1
-30	1	0	0	1	1	1	1	0	-78	1	1	0	0	1	1	1	0
-31	1	0	0	1	1	1	1	1	-79	1	1	0	0	1	1	1	1
-32	1	0	1	0	0	0	0	0	-80	1	1	1	1	1	1	1	1
02			<u> </u>		U	U											

3. Application Circuit



(Note) About single input 1 to 3, it is possible to change from single input to GND Isolation input 2.3. (Note) About GND Isolation1 and Full Differential, it is possible to change from differential input to single input 4 to 6.

Notes on wiring

- ① Please connect the decoupling capacitor of the power supply in the shortest possible distance to GND.
- ② GND lines should be one-point connected.
- ③ Wiring pattern of Digital shall be away from that of analog unit and crosstalk should not be acceptable.
- If possible, SCL and SDA lines of I²C BUS should not be in parallel. The lines should be shielded, if they are adjacent to each other.
- 5 If possible, analog input lines should not be in parallel. The lines should be shielded, if they are adjacent to each other.
- 6 TEST pins (Pin 14,15,16) should be OPEN.

Power Dissipation

About the thermal design of the IC

Characteristics of an IC are greatly affected by the temperature at which it is used. Exceeding absolute maximum ratings may degrade and destroy the device. Careful consideration must be given to the heat of the IC from the two standpoints of immediate damage and long-term reliability of operation.

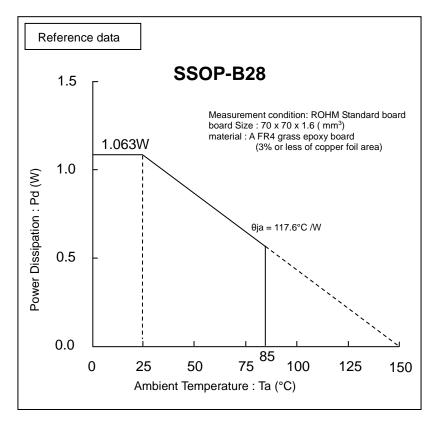


Figure 23. Temperature Derating Curve

(Note) Values are actual measurements and are not guaranteed.

Power dissipation values vary according to the board on which the IC is mounted.

I/O Equivalent Circuits

Equivalen	t Circuits			
Terminal	Terminal	Terminal	Equivalent Circuit	Terminal Description
No.	Name	Voltage		
1 2 3 4 5	A1 A2 B1 B2 C1 C2	4.25	VCC VB VB VB VB VB VB	A terminal for signal input. The input impedance is 100kΩ (Typ).
7 8 9 10 11 12 13	DP1 DN DP2 EP1 EN1 EN2 EP2	4.25	VCC O D D D S 250k	Input terminal available to single/Differential mode. The input impedance is 250kΩ (Typ).
15	MUTE	-	VCC A B B B 1.65V	A terminal for external compulsory mute. If terminal voltage is High level, the mute is OFF. And if the terminal voltage is Low level, the mute is ON.
18 19 20 21 22 23	OUTS2 OUTS1 OUTR2 OUTR1 OUTF2 OUTF1	4.25	VCC GND GND	A terminal for fader and Subwoofer output.

Values in the pin explanation and input/output equivalent circuit are for reference purposes only. It is not a guaranteed value.

I/O Equivalent Circuits - continued

Terminal No.	Terminal Name	Terminal Voltage	Equivalent Circuit	Terminal Description
24	VCC	8.5		Power supply terminal.
25	SCL	-	VCC O 1.65V	A terminal for clock input of I ² C BUS communication.
26	SDA	-	VCC O 1.65V	A terminal for data input of I ² C BUS communication.
27	GND	0		Ground terminal.
28	FIL	4.25	VCC Solve So	Voltage for reference bias of analog signal system. The simple pre-charge circuit and simple discharge circuit for an external capacitor are built in.
14 16 17	TEST	-		TEST terminal

Values in the pin explanation and input/output equivalent circuit are for reference purposes only. It is not a guaranteed value.

Operational Notes

1. Reverse Connection of Power Supply

Connecting the power supply in reverse polarity can damage the IC. Take precautions against reverse polarity when connecting the power supply, such as mounting an external diode between the power supply and the IC's power supply pins.

2. Power Supply Lines

Design the PCB layout pattern to provide low impedance supply lines. Separate the ground and supply lines of the digital and analog blocks to prevent noise in the ground and supply lines of the digital block from affecting the analog block. Furthermore, connect a capacitor to ground at all power supply pins. Consider the effect of temperature and aging on the capacitance value when using electrolytic capacitors.

3. Ground Voltage

Ensure that no pins are at a voltage below that of the ground pin at any time, even during transient condition.

4. Ground Wiring Pattern

When using both small-signal and large-current ground traces, the two ground traces should be routed separately but connected to a single ground at the reference point of the application board to avoid fluctuations in the small-signal ground caused by large currents. Also ensure that the ground traces of external components do not cause variations on the ground voltage. The ground lines must be as short and thick as possible to reduce line impedance.

5. Thermal Consideration

Should by any chance the power dissipation rating be exceeded the rise in temperature of the chip may result in deterioration of the properties of the chip. In case of exceeding this absolute maximum rating, increase the board size and copper area to prevent exceeding the Pd rating.

6. Recommended Operating Conditions

These conditions represent a range within which the expected characteristics of the IC can be approximately obtained. The electrical characteristics are guaranteed under the conditions of each parameter.

7. Inrush Current

When power is first supplied to the IC, it is possible that the internal logic may be unstable and inrush current may flow instantaneously due to the internal powering sequence and delays, especially if the IC has more than one power supply. Therefore, give special consideration to power coupling capacitance, power wiring, width of ground wiring, and routing of connections.

8. Operation Under Strong Electromagnetic Field

Operating the IC in the presence of a strong electromagnetic field may cause the IC to malfunction.

9. Testing on Application Boards

When testing the IC on an application board, connecting a capacitor directly to a low-impedance output pin may subject the IC to stress. Always discharge capacitors completely after each process or step. The IC's power supply should always be turned off completely before connecting or removing it from the test setup during the inspection process. To prevent damage from static discharge, ground the IC during assembly and use similar precautions during transport and storage.

10. Inter-pin Short and Mounting Errors

Ensure that the direction and position are correct when mounting the IC on the PCB. Incorrect mounting may result in damaging the IC. Avoid nearby pins being shorted to each other especially to ground, power supply and output pin. Inter-pin shorts could be due to many reasons such as metal particles, water droplets (in very humid environment) and unintentional solder bridge deposited in between pins during assembly to name a few.

11. Unused Input Pins

Input pins of an IC are often connected to the gate of a MOS transistor. The gate has extremely high impedance and extremely low capacitance. If left unconnected, the electric field from the outside can easily charge it. The small charge acquired in this way is enough to produce a significant effect on the conduction through the transistor and cause unexpected operation of the IC. So unless otherwise specified, unused input pins should be connected to the power supply or ground line.

Operational Notes - continued

12. Regarding the Input Pin of the IC

This monolithic IC contains P+ isolation and P substrate layers between adjacent elements in order to keep them isolated. P-N junctions are formed at the intersection of the P layers with the N layers of other elements, creating a parasitic diode or transistor. For example (refer to figure below):

When GND > Pin A and GND > Pin B, the P-N junction operates as a parasitic diode. When GND > Pin B, the P-N junction operates as a parasitic transistor.

Parasitic diodes inevitably occur in the structure of the IC. The operation of parasitic diodes can result in mutual interference among circuits, operational faults, or physical damage. Therefore, conditions that cause these diodes to operate, such as applying a voltage lower than the GND voltage to an input pin (and thus to the P substrate) should be avoided.

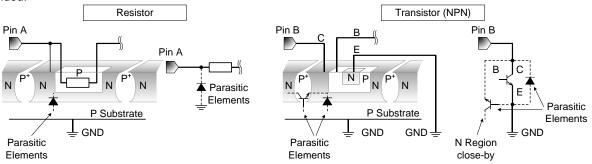
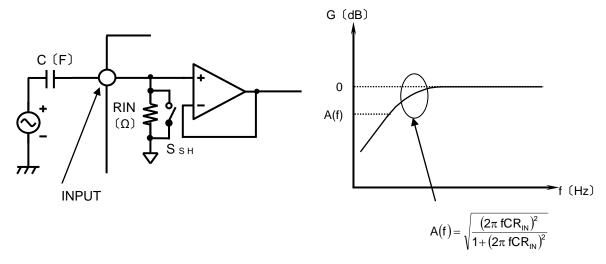


Figure 24. Example of monolithic IC structure

13. About a Signal Input Part

(a) About Input Coupling Capacitor Constant Value The constant value of input coupling capacitor C(F) is decided with respect to the input impedance R_{IN}(Ω) at the input signal terminal of the IC that would be sufficient to form an RC characterized HPF.



(b) About the Input Selector SHORT SHORT mode is the command which makes switch S_{SH} =ON of input selector part so that the input impedance R_{IN} of all terminals becomes small. Switch S_{SH} is OFF when SHORT command is not selected. The constant time brought about by the small resistance inside and the capacitor outside the LSI becomes small when this command is used. The charge time of the capacitor becomes short. Since SHORT mode turns ON the switch of S_{SH} and makes it low impedance, please use it at no signal condition.

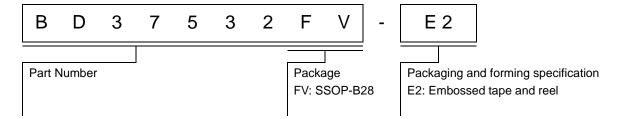
14. About Mute Terminal (Pin 15) when Power Supply is OFF

There should be no applied voltage to Mute terminal (Pin 15) when power-supply is OFF. If in case voltage is supplied to Mute terminal, please insert a series resistor (about $2.2k\Omega$) to Mute terminal. (Please refer to Application Circuit Diagram.)

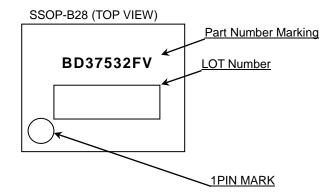
15. About TEST Pin

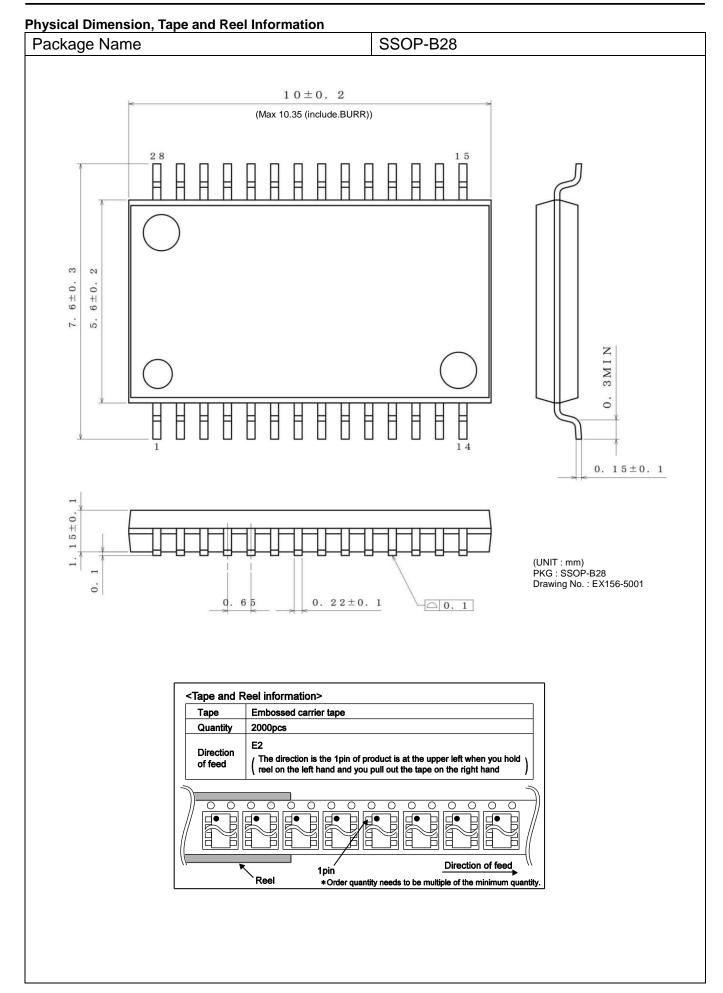
TEST Pin should be OPEN. Pin 14. 16, 17 are TEST Pins

Ordering Information



Marking Diagram





Revision History

Date	Revision	Changes
16.Dec.2015	001	New Release

Notice

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 - [h] Use of the Products in places subject to dew condensation
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- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

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 - [d] the Products are exposed to high Electrostatic
- Even under ROHM recommended storage condition, solderability of products out of recommended storage time period
 may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is
 exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
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